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PATENT & TRADEMARK OFFICE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/681,572

Filed: October 8, 2003

Title: **Semiconductor multi-package module having inverted second package**

Examiner: Alonzo Chambliss

Group Art Unit: 2814

Date: 03 May 2005

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 03 May 2005.

Signed _____
Paula Faulk Hurley

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office action mailed November 3, 2004, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

There are no amendments to the claims; a **Listing of Claims** begins on page 5 of this paper.

Amendments to the Drawings begin on page 8 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 9 of this paper.

An **Appendix** including amended drawing figures is attached following page # of this paper.